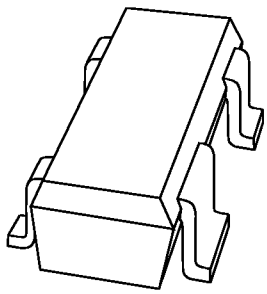
DATA SHEET



BFG505W; BFG505W/X
NPN 9 GHz wideband transistors

Product specification
Supersedes data of August 1995

1998 Oct 02

Philips
Semiconductors

PHILIPS

NPN 9 GHz wideband transistors BFG505W; BFG505W/X

FEATURES

- High power gain
- Low noise figure
- High transition frequency
- Gold metallization ensures excellent reliability.

APPLICATIONS

RF front end applications in the GHz range, such as analog and digital cellular telephones, cordless telephones (CT2, CT3, PCN, DECT, etc.), radar detectors, pagers, satellite television tuners (SATV).

DESCRIPTION

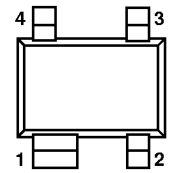
NPN silicon planar epitaxial transistor in a 4-pin dual-emitter SOT343N plastic package.

MARKING

TYPE NUMBER	CODE
BFG505W	N0
BFG505W/X	N1

PINNING

PIN	DESCRIPTION	
	BFG505W	BFG505W/X
1	collector	collector
2	base	emitter
3	emitter	base
4	emitter	emitter



Top view MBK523

Fig.1 Simplified outline SOT343N.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	–	20	V
V_{CES}	collector-emitter voltage	R_{BE} = 0	–	–	15	V
I_C	collector current (DC)		–	–	18	mA
P_{tot}	total power dissipation	$T_s \leq 85$ °C	–	–	500	mW
h_{FE}	DC current gain	I_C = 5 mA; V_{CE} = 6 V	60	120	250	
C_{re}	feedback capacitance	I_C = 0; V_{CB} = 6 V; f = 1 MHz	–	0.2	–	pF
f_T	transition frequency	I_C = 5 mA; V_{CE} = 6 V; f = 1 GHz; T_{amb} = 25 °C	–	9	–	GHz
G_{UM}	maximum unilateral power gain	I_C = 5 mA; V_{CE} = 6 V; f = 900 MHz; T_{amb} = 25 °C	–	19	–	dB
		I_C = 5 mA; V_{CE} = 6 V; f = 2 GHz; T_{amb} = 25 °C		12	–	dB
$\|S_{21}\|^2$	insertion power gain	I_C = 5 mA; V_{CE} = 6 V; f = 900 MHz; T_{amb} = 25 °C	15	16	–	dB
F	noise figure	$\Gamma_s = \Gamma_{opt}$; I_C = 1.25 mA; V_{CE} = 6 V; f = 2 GHz	–	1.9	–	dB

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	20	V
V_{CES}	collector-emitter voltage	R_{BE} = 0	–	15	V
V_{EBO}	emitter-base voltage	open collector	–	2.5	V
I_C	collector current (DC)		–	18	mA
P_{tot}	total power dissipation	$T_s \leq 85$ °C; see Fig.2; note 1	–	500	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	175	°C

Note

1. T_s is the temperature at the soldering point of the collector pin.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j\text{-}s}$	thermal resistance from junction to soldering point	$T_s \leq 85$ °C; note 1	180	K/W

Note

1. T_s is the temperature at the soldering point of the collector pin.

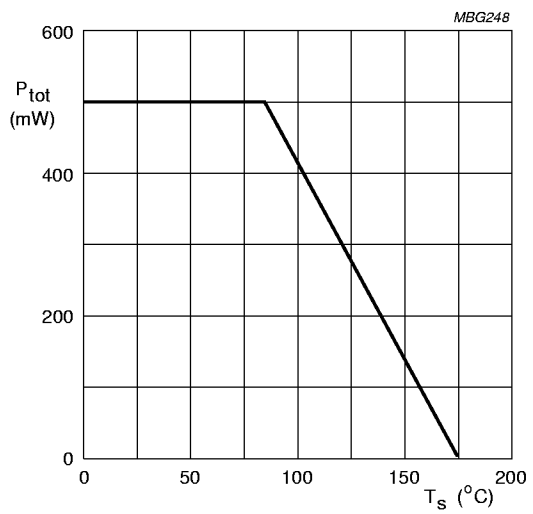


Fig.2 Power derating curve.

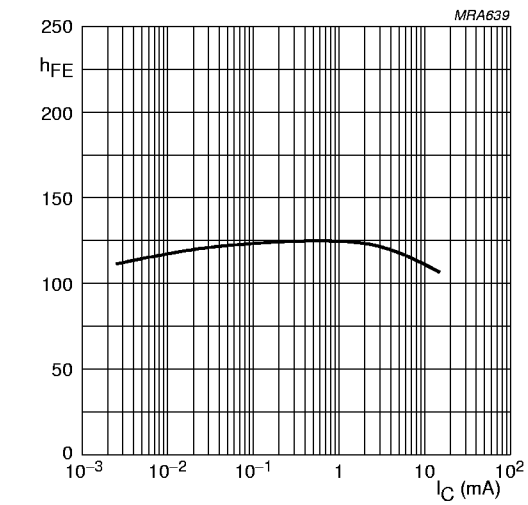
CHARACTERISTICS

T_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)CBO}$	collector-base breakdown voltage	I_C = 2.5 μA ; I_E = 0	20	–	–	V
$V_{(BR)CES}$	collector-emitter breakdown voltage	I_C = 10 μA; R_{BE} = 0	15	–	–	V
$V_{(BR)EBO}$	emitter-base breakdown voltage	I_E = 2.5 μA; I_C = 0	2.5	–	–	V
I_{CBO}	collector leakage current	V_{CB} = 6 V; I_E = 0	–	–	50	nA
h_{FE}	DC current gain	I_C = 5 mA; V_{CE} = 6 V see Fig.3	60	120	250	
f_T	transition frequency	I_C = 5 mA; V_{CE} = 6 V; f = 1 GHz; T_{amb} = 25 °C; see Fig.5	–	9	–	GHz
C_c	collector capacitance	$I_E = i_e$ = 0; V_{CB} = 6 V; f = 1 MHz	–	0.3	–	pF
C_e	emitter capacitance	$I_C = i_c$ = 0; V_{EB} = 0.5 V; f = 1 MHz	–	0.4	–	pF
C_{re}	feedback capacitance	I_C = 0; V_{CB} = 6 V; f = 1 MHz; see Fig.4	–	0.2	–	pF
G_{UM}	maximum unilateral power gain; note 1	I_C = 5 mA; V_{CE} = 6 V; f = 900 MHz; T_{amb} = 25 °C	–	19	–	dB
		I_C = 5 mA; V_{CE} = 6 V; f = 2 GHz; T_{amb} = 25 °C	–	12	–	dB
$\lvert S_{21}\rvert^2$	insertion power gain	I_C = 5 mA; V_{CE} = 6 V; f = 900 MHz; T_{amb} = 25 °C	15	16	–	dB
F	noise figure	$\Gamma_s = \Gamma_{opt}$; I_C = 1.25 mA; V_{CE} = 6 V; f = 900 MHz	–	1.2	1.7	dB
		$\Gamma_s = \Gamma_{opt}$; I_C = 5 mA; V_{CE} = 6 V; f = 900 MHz	–	1.6	2.1	dB
		$\Gamma_s = \Gamma_{opt}$; I_C = 1.25 mA; V_{CE} = 6 V; f = 2 GHz	–	1.9	–	dB
P_{L1}	output power at 1 dB gain compression	I_C = 5 mA; V_{CE} = 6 V; f = 900 MHz; R_L = 50 Ω; T_{amb} = 25 °C	–	4	–	dBm
ITO	third order intercept point	note 2	–	10	–	dBm

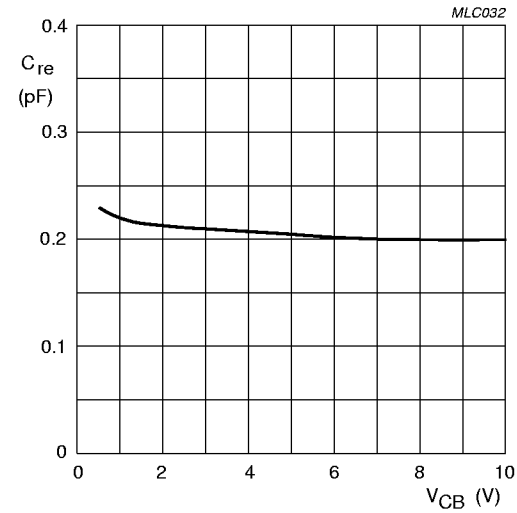
Notes

1. G_{UM} is the maximum unilateral power gain, assuming S_{12} is zero. $G_{UM} = 10 \log \frac{|S_{21}|^2}{(1-|S_{11}|^2)(1-|S_{22}|^2)}$ dB.
2. I_C = 5 mA; V_{CE} = 6 V; R_L = 50 Ω; T_{amb} = 25 °C;
   f_p = 900 MHz; f_q = 902 MHz;
   measured at $2f_p - f_q$ = 898 MHz and $2f_q - f_p$ = 904 MHz.



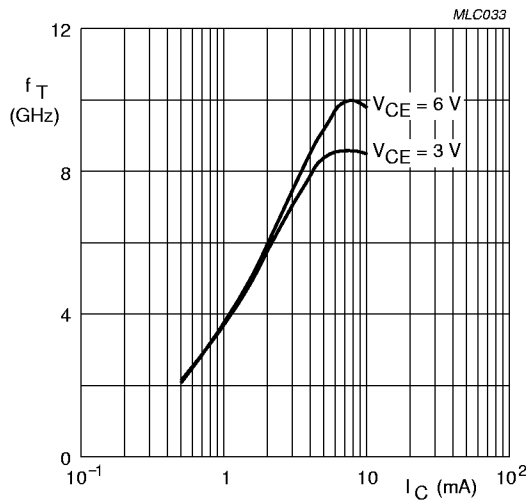
V_{CE} = 6 V.

Fig.3 DC current gain as a function of collector current; typical values.



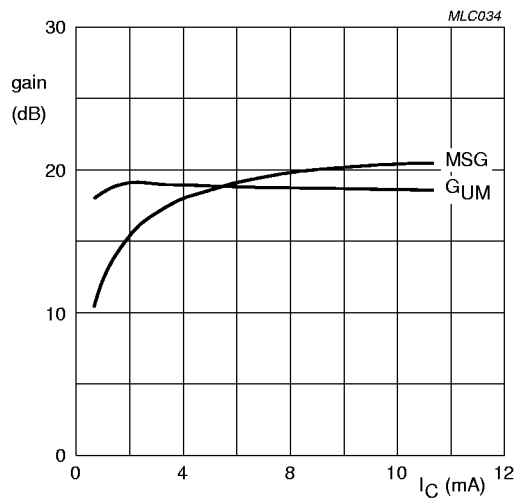
I_C = 0; f = 1 MHz.

Fig.4 Feedback capacitance as a function of collector-base voltage; typical values.



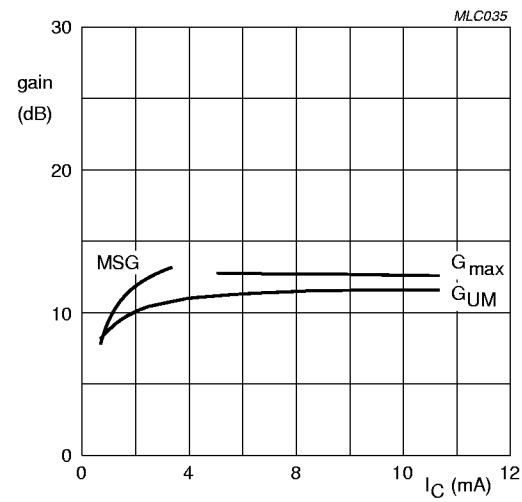
f = 1 GHz; T_{amb} = 25 °C.

Fig.5 Transition frequency as a function of collector current; typical values.



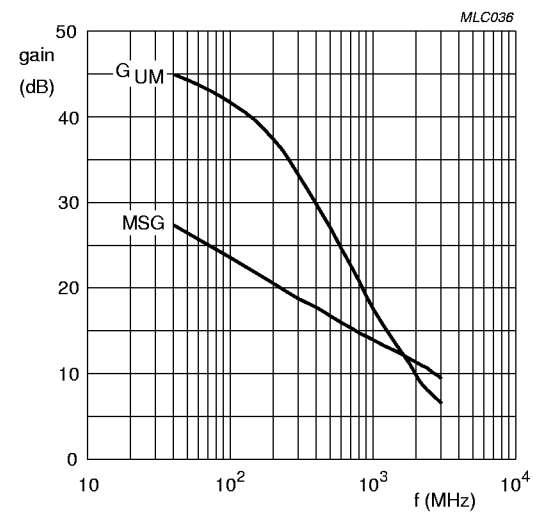
f = 900 MHz; V_{CE} = 6 V.

Fig.6 Gain as a function of collector current; typical values.



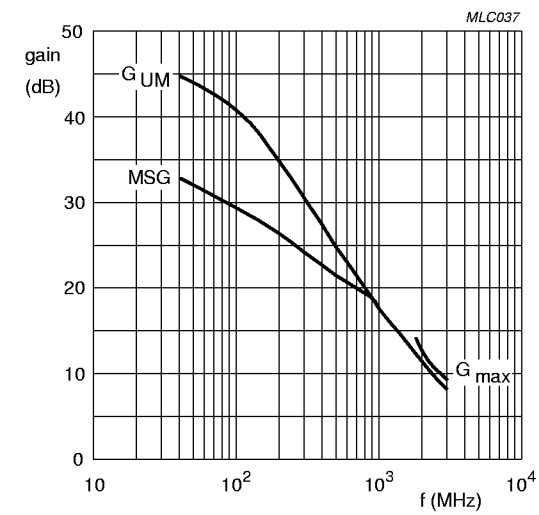
f = 2 GHz; V_{CE} = 6 V.

Fig.7 Gain as a function of collector current; typical values.



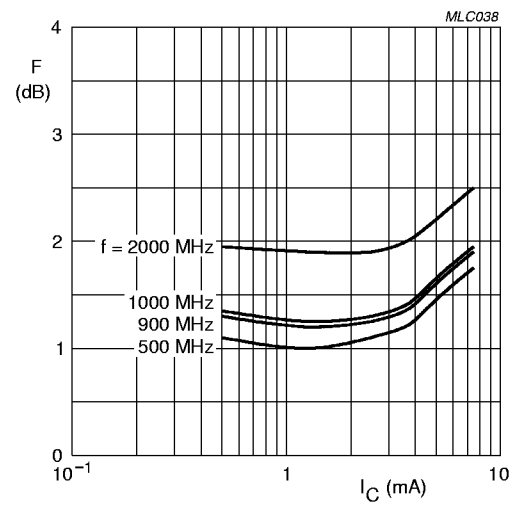
I_C = 1.25 mA; V_{CE} = 6 V.

Fig.8 Gain as a function of frequency; typical values.



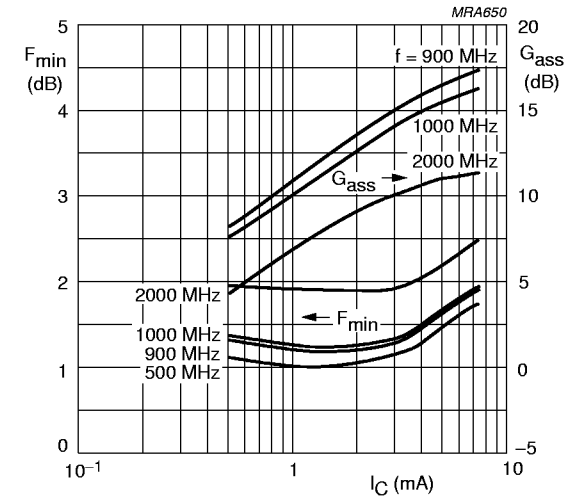
I_C = 5 mA; V_{CE} = 6 V.

Fig.9 Gain as a function of frequency; typical values.



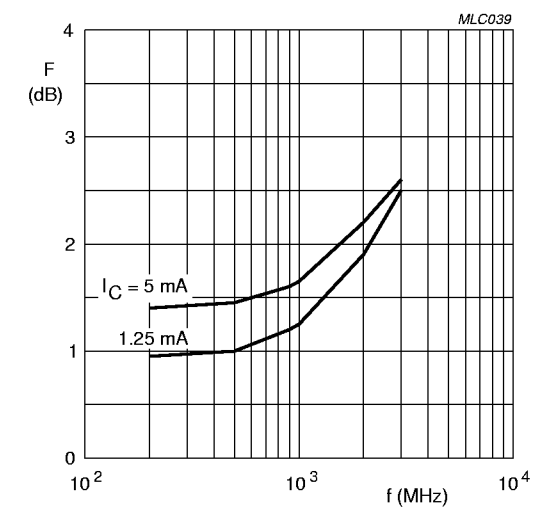
V_{CE} = 6 V.

Fig.10 Minimum noise figure as a function of collector current; typical values.



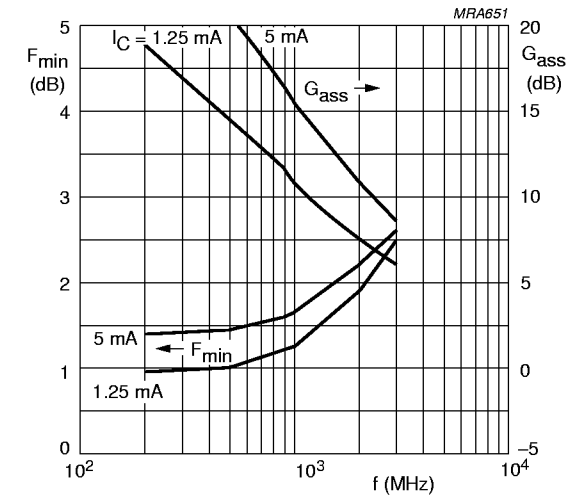
V_{CE} = 6 V.

Fig.11 Associated available gain as a function of collector current; typical values.



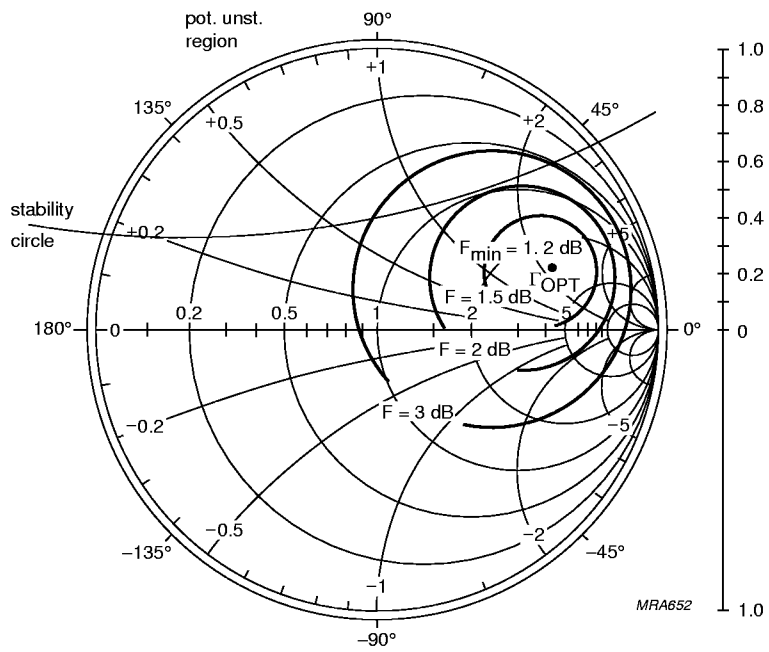
V_{CE} = 6 V.

Fig.12 Minimum noise figure as a function of frequency; typical values.



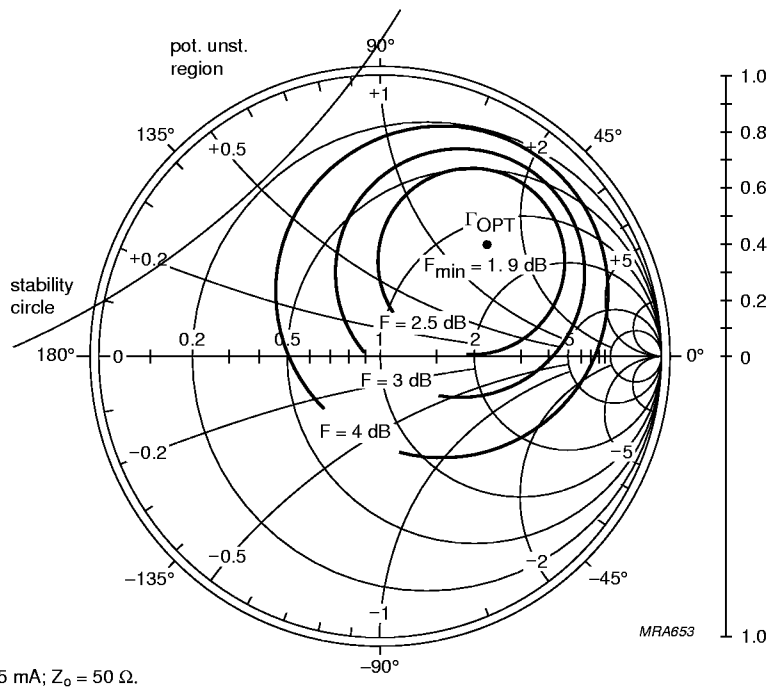
V_{CE} = 6 V.

Fig.13 Associated available gain as a function of frequency; typical values.



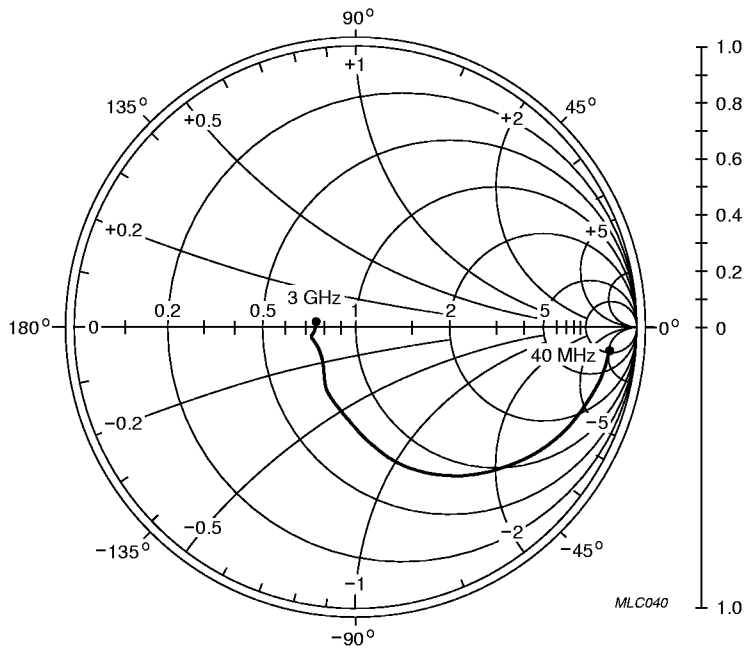
f = 900 MHz; V_{CE} = 6 V; I_C = 1.25 mA; Z_o = 50 Ω.

Fig.14 Common emitter noise figure circles; typical values.



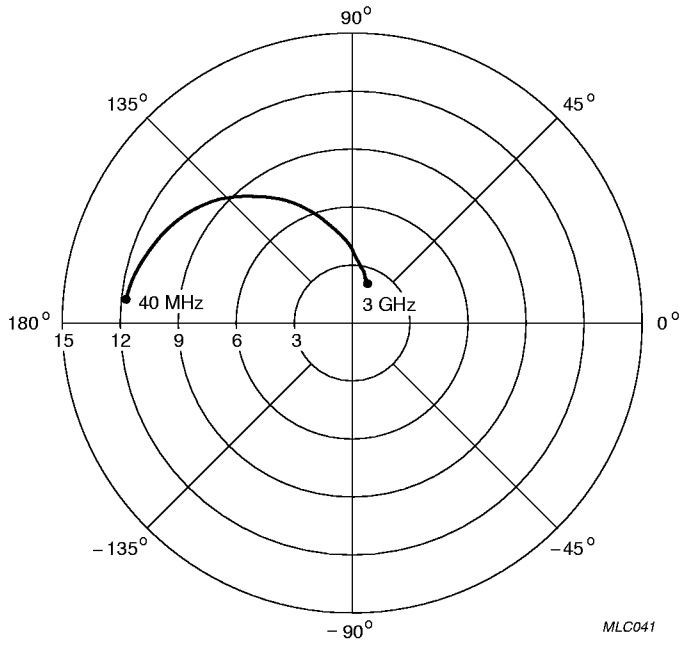
f = 2 GHz; V_{CE} = 6 V; I_C = 1.25 mA; Z_o = 50 Ω.

Fig.15 Common emitter noise figure circles; typical values.



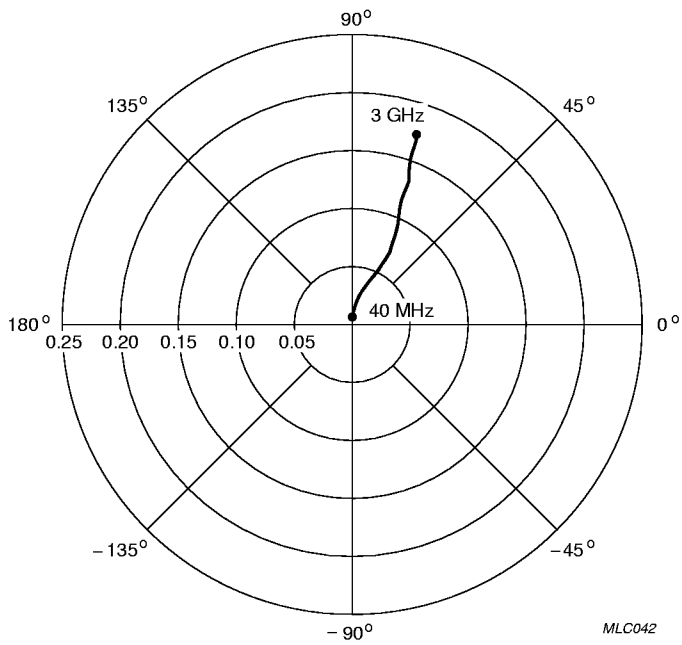
V_{CE} = 6 V; I_C = 5 mA; Z_o = 50 Ω.

Fig.16 Common emitter input reflection coefficient (S_{11}); typical values.



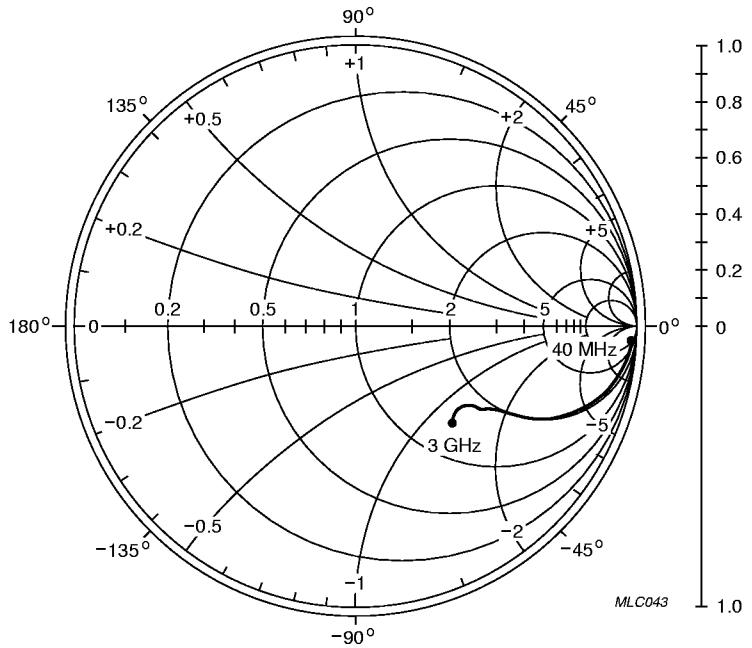
V_{CE} = 6 V; I_C = 5 mA.

Fig.17 Common emitter forward transmission coefficient (S_{21}); typical values.



V_{CE} = 6 ; I_C = 5 mA.

Fig.18 Common emitter reverse transmission coefficient (S_{12}); typical values.



V_{CE} = 6 V; I_C = 5 mA; Z_o = 50 Ω.

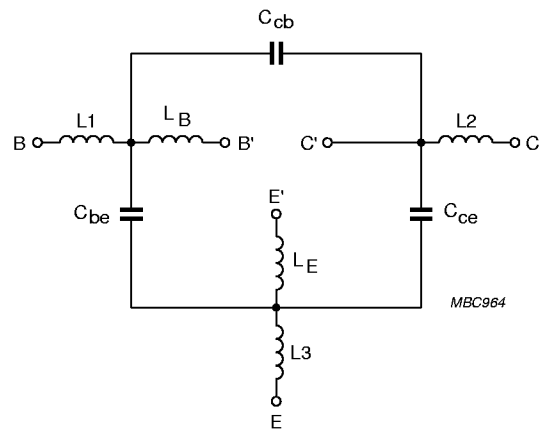
Fig.19 Common emitter output reflection coefficient (S_{22}); typical values.

SPICE parameters for the BFG505W(/X) die

SEQUENCE No.	PARAMETER	VALUE	UNIT
1	IS	134.1	aA
2	BF	180.0	–
3	NF	0.988	–
4	VAF	38.34	V
5	IKF	150.0	mA
6	ISE	27.81	fA
7	NE	2.051	–
8	BR	55.19	–
9	NR	0.982	–
10	VAR	2.459	V
11	IKR	2.920	mA
12	ISC	17.45	aA
13	NC	1.062	–
14	RB	20.00	Ω
15	IRB	1.000	μA
16	RBM	20.00	Ω
17	RE	1.171	Ω
18	RC	4.350	Ω
19 (1)	XTB	0.000	–
20 (1)	EG	1.110	eV
21 (1)	XTI	3.000	–
22	CJE	284.7	fF
23	VJE	600.0	mV
24	MJE	0.303	–
25	TF	7.037	ps
26	XTF	12.34	–
27	VTF	1.701	V
28	ITF	30.64	mA
29	PTF	0.000	deg
30	CJC	242.4	fF
31	VJC	188.6	mV
32	MJC	0.041	–
33	XCJC	0.130	–
34	TR	1.332	ns
35 (1)	CJS	0.000	F
36 (1)	VJS	750.0	mV
37 (1)	MJS	0.000	–
38	FC	0.897	–

Note

1. These parameters have not been extracted, the default values are shown.



$QL_B = 50$; $QL_E = 50$; $QL_{B,E}(f) = QL_{B,E}\sqrt{(f/f_c)}$
f_c = scaling frequency = 1 GHz.

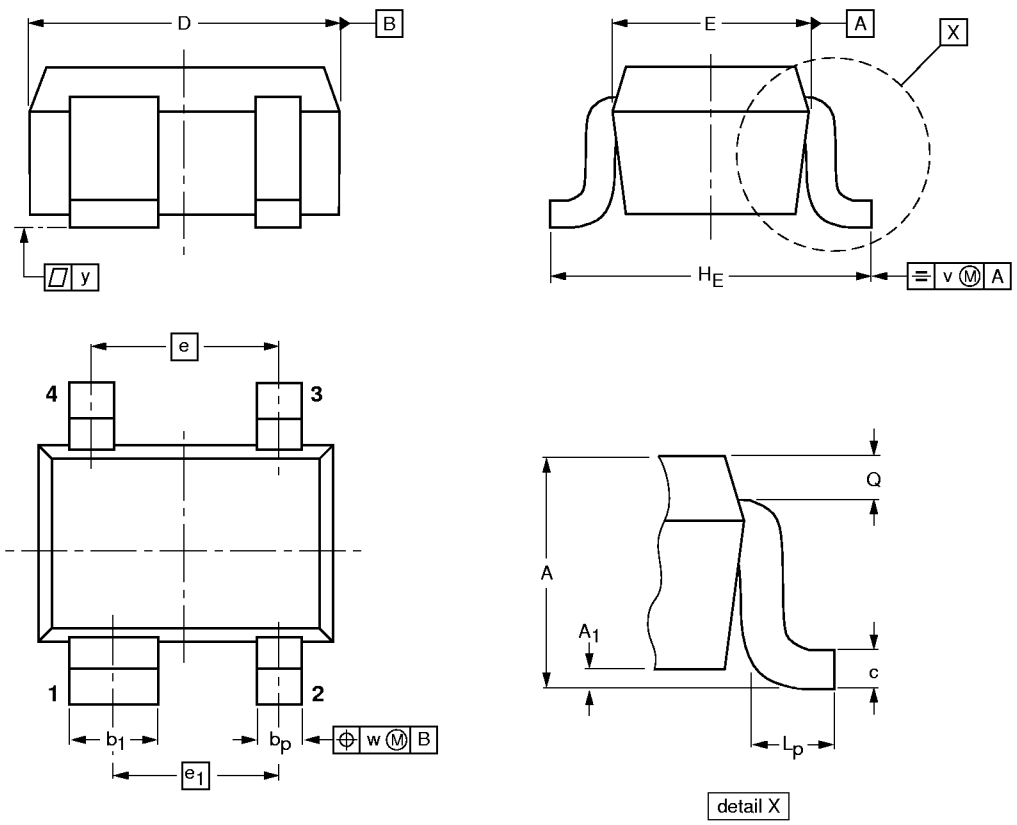
Fig.20 Package equivalent circuit SOT343N.

List of components (see Fig.20)

DESIGNATION	VALUE	UNIT
C_{be}	70	fF
C_{cb}	50	fF
C_{ce}	115	fF
L1	0.34	nH
L2	0.10	nH
L3	0.25	nH
L_B	0.40	nH
L_E	0.40	nH

PACKAGE OUTLINE

Plastic surface mounted package; 4 leads **SOT343N**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max	b_p	b_1	c	D	E	e	e_1	H_E	L_p	Q	v	w	y
mm	1.1 0.8	0.1	0.4 0.3	0.7 0.5	0.25 0.10	2.2 1.8	1.35 1.15	1.3	1.15	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT343N						97-05-21